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Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D <i>* : Required Field</i>

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2015-12-18
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	Floriana San Biagio	Representative Title	AMS MD CHAMPION
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

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Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard
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Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	CDO7*0082BF6	A	BO2A	2015-12-18
Amount	UoM	Unit type	ST ECOPACK Grade	
80.00	mg	Each	ECOPACK® 3	
	Comment	ECOPACK® 3 is STMicroelectronics trade name for ROHS compliant device without use of any ROHS exemption and without Halogen nor Antimony		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Tin (Sn), matte, annealed	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
DSO	4.85 x 3.9 x 1.52	8	gull wing	
Comment	Package for: O7 SO 08 .15 JEDEC; MDF valid for LF353DT			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	true
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Exemption Id.	Description

QueryList : REACH-15th June 2015				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	CDO7*0082BF6					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	1.363	mg	supplier	die	Silicon (Si)	7440-21-3		1.332	mg	977256	16650
				supplier	metallization	Aluminium (Al)	7429-90-5		0.011	mg	8070	138
				supplier	Passivation	Silicon Nitride	12033-89-5		0.006	mg	4402	75
				supplier	Passivation	Silicon Oxide	7631-86-9		0.007	mg	5136	88
				supplier	glass coating	Glass: Silicon Dioxide	7631-86-9		0.007	mg	5136	88
Leadframe	Copper & its alloys	29.683	mg	supplier	alloy	Copper (Cu)	7440-50-8		27.902	mg	939999	348775
				supplier	alloy	Iron (Fe)	7439-89-6		0.656	mg	22100	8200
				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.040	mg	1348	500
				supplier	alloy	Zinc (Zn)	7440-66-6		0.034	mg	1145	425
				supplier	metallization	Nickel (Ni)	7440-02-0		0.486	mg	16373	6075
				supplier	metallization	Palladium (Pd)	7440-05-3		0.031	mg	1044	388
				supplier	metallization	Gold (Au)	7440-57-5		0.013	mg	438	163
				supplier	metallization	Silver (Ag)	7440-22-4		0.521	mg	17552	6513
				supplier	glue	Silver (Ag)	7440-22-4		0.471	mg	909266	5888
Die attach	Other Organic Materials	0.518	mg	supplier	glue	acrylate	Proprietary		0.026	mg	50193	325
				supplier	glue	Methacrylate	Proprietary		0.021	mg	40541	263
				supplier	wire	Copper (Cu)	7440-50-8		0.072	mg	1000000	900
Bonding wires	Other inorganic materials	0.072	mg	supplier	wire	Copper (Cu)	7440-50-8		0.072	mg	1000000	900
				supplier	wire	Copper (Cu)	7440-50-8		0.072	mg	1000000	900
Encapsulation	Other Organic Materials	47.617	mg	supplier	mold compound	Silica, vitreous	60676-86-0		41.237	mg	866014	515463
				supplier	mold compound	Epoxy Resin	Proprietary		3.571	mg	74994	44638
				supplier	mold compound	Phenol Resin	Proprietary		2.381	mg	50003	29763
				supplier	mold compound	Carbon black	1333-86-4		0.238	mg	4998	2975
connections coating	Solder	0.747	mg	supplier	mold compound	Bismuth (Bi)	7440-69-9		0.190	mg	3990	2375
				supplier	solder alloy	Tin (Sn)	7440-31-5		0.747	mg	1000000	9338